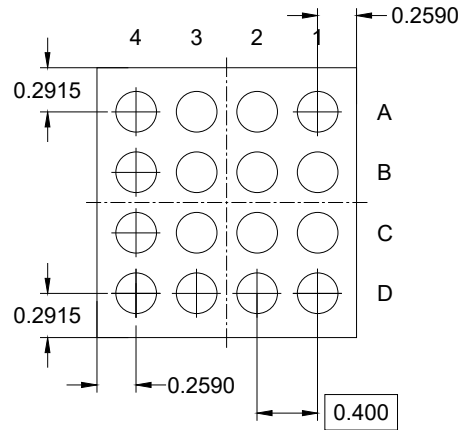
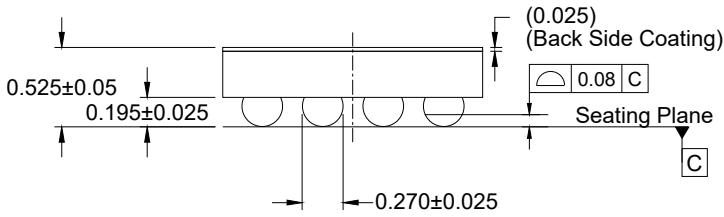


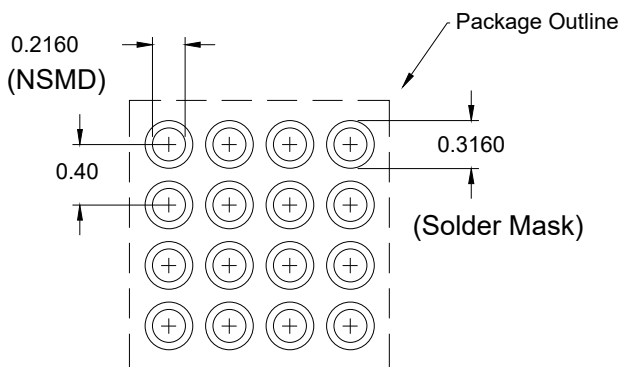
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN
(PCB Top View, NSMD Design)

NOTES:

1. JEDEC compatible.
2. All dimension are in mm and angles are in degrees.
3. Use $\pm 0.05\text{mm}$ for the non-tolerenced dimensions.
4. Numbers in () are for references only.
5. Pre-reflow solder ball diameter is $\text{Ø}0.25$ mm.
6. UBM diameter is $\text{Ø}0.24$ mm.